

PRELIMINARY AMENDMENT
New U.S. Application for PCT/JP99/05003


REMARKS

Claims 17, 18, 19, 21, and 44 have been amended to place the claims in desired appropriate form for examination. Thus all of the claims are now in appropriate form, and the Examiner is respectfully requested to proceed with the examination.

Early favorable action is earnestly solicited.

In the event that the Examiner believes that it may facilitate the further prosecution of this application, the Examiner is invited to contact the undersigned attorney at the local Washington, D.C. telephone number indicated below.

Respectfully submitted,


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APPENDIX

VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS:

The claims are amended as follows:

17. The electroless plating solution according to ~~any of Claims 14 to 16~~ Claim 14, the temperature of which is 25 to 40°C.
18. The electroless plating solution according to ~~any of Claims 14 to 17~~ Claim 14 wherein the copper deposition rate of said electroless plating solution is 1 to 2 µm/hour.
19. An electroless plating process which comprises immersing a substrate in the electroless plating solution according to ~~any of Claims 14 to 17~~ Claim 14 and performing electroless copper plating at a deposition rate set to 1 to 2 µm/hour.
21. A process for manufacturing a printed circuit board which comprises immersing a resin insulating substrate board in the electroless plating solution according to ~~any of Claims 14 to 17~~ Claim 14 and performing electroless copper plating at a deposition rate set to 1 to 2 µm/hour to provide a conductor circuit.
44. The multilayer printed circuit board according to ~~any of Claims 40 to 43~~ Claim 40 wherein said lower-layer via holes are filled with metal.

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